FQP44N10F
100V N-Channel MOSFET

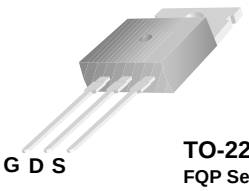
Features

- 43.5A, 100V, $R_{DS(on)}$ = 0.039Ω @V_{GS} = 10 V
- Low gate charge (typical 48 nC)
- Low Crss (typical 85 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- 175°C maximum junction temperature rating

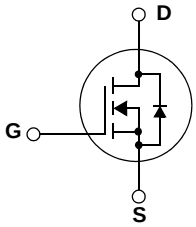
Description

These N-Channel enhancement mode power field effect tran-sist-ors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performanc-e, and withstand high energy pulse in the avalanche and co-mmutation mode. These devices are well suited for low voltage applications such as audio amplifier, high efficiency switching DC/DC converters, and DC motor control.



TO-220
FQP Series



Absolute Maximum Ratings

Symbol	Parameter		FQP44N10F	Units
V_{DSS}	Drain-Source Voltage		100	V
I_D	Drain Current - Continuous (T_C = 25°C)		43.5	A
	Drain Current - Continuous (T_C = 100°C)		30.8	A
I_{DM}	Drain Current - Pulsed	(Note 1)	174	A
V_{GSS}	Gate-Source Voltage		± 25	V
E_{AS}	Single Pulsed Avalanche Energy	(Note 2)	530	mJ
I_{AR}	Avalanche Current	(Note 1)	43.5	A
E_{AR}	Repetitive Avalanche Energy	(Note 1)	14.6	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	15	V/ns
P_D	Power Dissipation (T_C = 25°C)		146	W
	- Derate above 25°C		0.97	W/°C
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +175	°C
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

Thermal Characteristics

Symbol	Parameter	FQP44N10F	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.03	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FQP44N10F	FQP44N10F	TO-220	--	--	50

Electrical Characteristics T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0 V, I_D = 250 μA	100	--	--	V
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temperature Coefficient	I_D = 250 μA, Referenced to 25°C	--	0.1	--	V/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 100 V, V_{GS} = 0 V	--	--	10	μA
		V_{DS} = 80 V, T_C = 150°C	--	--	100	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	V_{GS} = 25 V, V_{DS} = 0 V	--	--	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	V_{GS} = -25 V, V_{DS} = 0 V	--	--	-100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 250 μA	2.0	--	4.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	V_{GS} = 10 V, I_D = 21.75 A	--	0.03	0.039	Ω
g_{FS}	Forward Transconductance	V_{DS} = 40 V, I_D = 21.75 A (Note 4)	--	30	--	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = 25 V, V_{GS} = 0 V, f = 1.0 MHz	--	1400	1800	pF
C_{oss}	Output Capacitance		--	425	550	pF
C_{rss}	Reverse Transfer Capacitance		--	85	110	pF
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{DD} = 50 V, I_D = 43.5A, R_G = 25 Ω	--	19	45	ns
t_r	Turn-On Rise Time		--	190	390	ns
$t_{d(off)}$	Turn-Off Delay Time		--	90	190	ns
t_f	Turn-Off Fall Time	(Note 4, 5)	--	100	210	ns
Q_g	Total Gate Charge	V_{DS} = 80 V, I_D = 43.5A, V_{GS} = 10 V	--	48	62	nC
Q_{gs}	Gate-Source Charge		--	9.0	--	nC
Q_{gd}	Gate-Drain Charge	(Note 4, 5)	--	24	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain-Source Diode Forward Current		--	--	43.5	A
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	174	A
V_{SD}	Drain-Source Diode Forward Voltage	V_{GS} = 0 V, I_S = 43.5 A	--	--	1.5	V
t_{rr}	Reverse Recovery Time	V_{GS} = 0 V, I_S = 43.5 A, dI_F / dt = 100 A/μs (Note 4)	--	70	--	ns
Q_{rr}	Reverse Recovery Charge		--	175	--	nC

NOTES:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. L = 0.42mH, I_{AS} = 43.5A, V_{DD} = 25V, R_G = 25 Ω, Starting T_J = 25°C
3. I_{SD} ≤ 43.5A, di/dt ≤3200A/μs, V_{DD} ≤ $BV_{DSS,}$ Starting T_J = 25°C
4. Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2%
5. Essentially independent of operating temperature

Typical Performance Characteristics

Figure 1. On-Region Characteristics

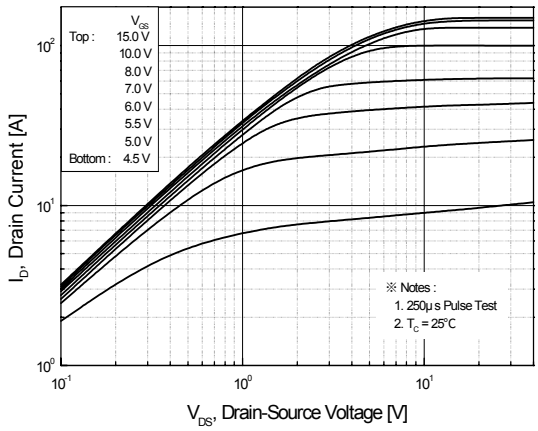


Figure 2. Transfer Characteristics

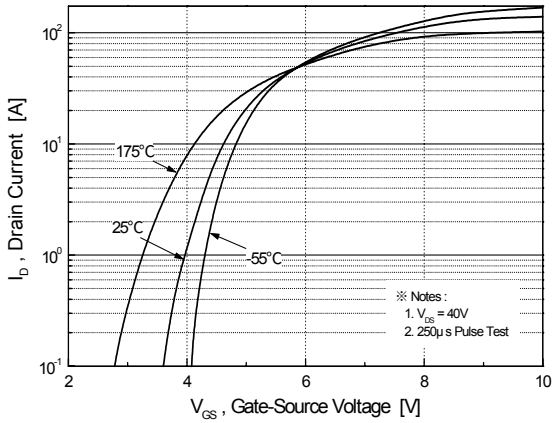


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

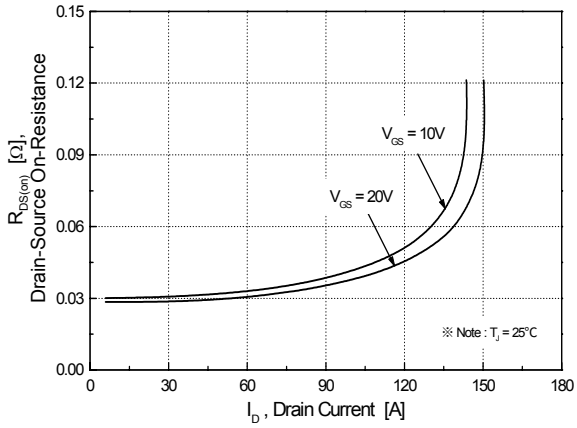


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

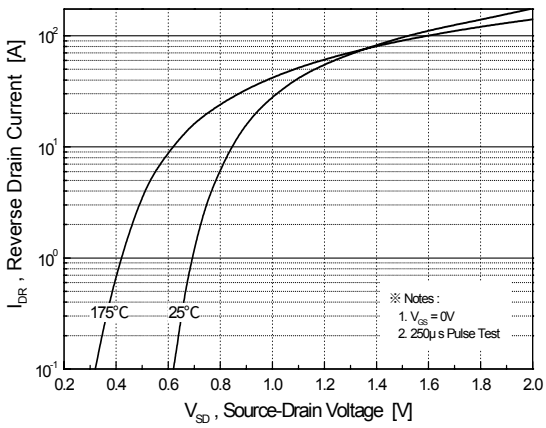


Figure 5. Capacitance Characteristics

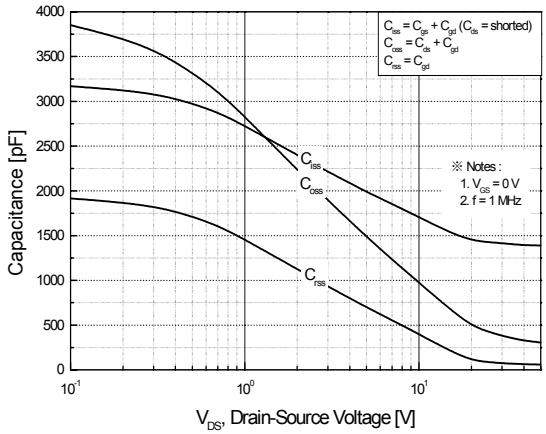


Figure 6. Gate Charge Characteristics